

# 2018 IEEE INTERNATIONAL RF & MICROWAVE CONFERENCE

## **INVITATION TO SPONSOR**

IEEE AP/MTT/EMC Joint Chapter will again be organizing IEEE International RF & Microwwave Conference. The 7th edition of the meeting (RFM2018) will be held from 17th - 19th December at Parkroyal Resort Penang. RFM2018 will include the following:

> • Tutorial on the 17th Dec 2018 • Three keynote talks on the 18th Dec 2018 • Technical tracks from 18th - 19th Dec 2018 • Exhibition from 18th - 19th Dec 2018 Conference Dinner on the 18th Dec 2018

Technical sessions will be featuring: • Three conference tracks Invited Speakers

Industry Special Session

• Women in Microwaves Special session

This year, RFM2018 received more than 140 papers and expecting participants from various organizations: government agency, industry and university. We are confident that RFM2018 is an event awaited by many researchers and engineers in the field of communications electronics, especially in antenna, propagation and microwave engineering. We have followers of RFM since it was conceived in 2004.

As one of our valued partner, your organization is invited to take part in RFM2018 as our sponsor. We believe your participation in RFM2018 will bring more opportunities in many ways for your organization. Please review the sponsorship package and contact our sponsorship chair for further information.

## **VISIT OUR PAGE: RFM2018.APMTTEMC.ORG**

Organised by: AP/MTT/EMC Joint Chapter, 1EEE Malaysia



Supported by:





2018

### **PROFESSOR NAOKI SHINOHARA**

**Current Research and Development of Wireless** Power Transfer via Radio Waves and the Application



### **PROF TIAN HONG LOH** Research trends in antennas and testbeds for 5G and beyond



### **DR MOHANRAJ SOUNDARA** PANDIAN

SilTerra's monolithically Integrated RFMEMS platform for active circuits and passive components





**ASSOCIATE PROF. DR** WONG PENG WEN An Overview of 5G Filtering - Challenges and **Opportunities** 



convention & exhibition bureau





2018

## **SPONSORSHIP PACKAGE**

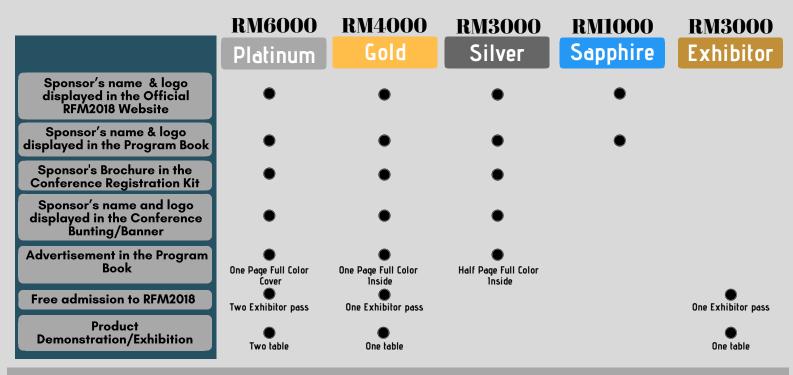
Submit your interest to:

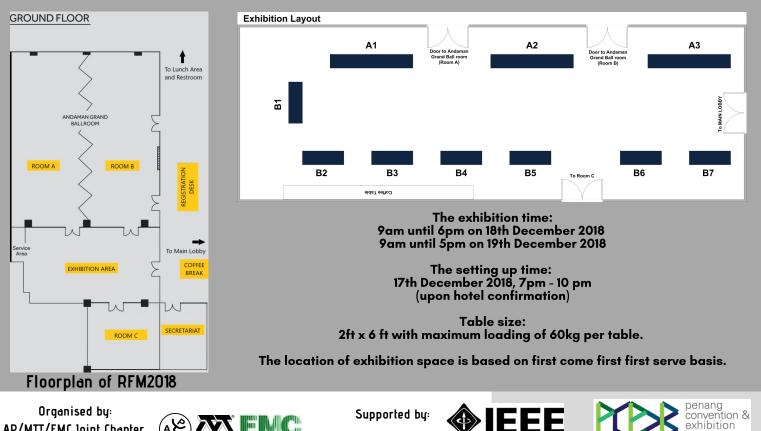
**Sponsorship Chair:** Badrul Hisham Ahmad badrulhisham@utem.edu.my

**Exhibition Chair:** Mohd Haizal Jamaluddin haizal@fke.utm.my

rfm2018.apmttemc.org contact@rfm2018.apmttemc.org

bureau





Malaysia Section

AP/MTT/EMC Joint Chapter, **IEEE Malaysia** 



## 2018 IEEE INTERNATIONAL RF & MICROWAVE CONFERENCE



Submit your Sponsorship Chair: Badrul Hisham Ahmad interest to: badrulhisham@utem.edu.my Exhibition Chair: Mohd Haizal Jamaluddin haizal@fke.utm.my

rfm2018.apmttemc.org contact@rfm2018.apmttemc.org

### **PACKAGE DETAIL:**

**Sponsor's name and logo displayed in the Official RFM2018 Website:** Sponsor's name and logo will be displayed in the official conference website (rfm2018.apmttemc.org) and hyperlinked to the sponsor determined website. The logo and website link should be submitted by 1 Nov 2018. The image file should be in .png or .jpg with transparent background. In the case of package sharing, only one company logo per package will be displayed in the website.

**Sponsor's name and logo displayed in the Program Book:** Program book will be provided for each of conference participants. Sponsor's name and logo will be displayed at the list of sponsor page. In the case of package sharing, only one logo per package is displayed in the program book. The sponsor's logo should be submitted by 1 Nov 2018. The image file should be in .png or .jpg with transparent background.

S**ponsor Brochure in the Conference Registration Kit:** Sponsor may provide marketing brochures to be included in the conference kit. Maximum of 150 copies should be delivered to the conference venue by 7pm, December 17th 2018.

**Sponsor's name and logo displayed in the Conference Bunting/Banner:** Sponsor's name and logo will be displayed in the official conference bunting and banner. The logo and website link should be submitted by 1 Nov 2018. The image file should be in .png or .jpg with transparent background. In the case of package sharing, only one logo per package is displayed in the conference bunting/banner.

Advertisement in the Program Book: Sponsor is entitled to One (Platinum) or Half (Gold) advertisement page in the program book. Only two Platinum sponsors are offered for the back cover advertisement and the priority to choose either outside or inside back cover will be given to the sponsor who made the payment first. The size of the program book is A4 size. Sponsor is expected to email the full color graphic fle in high resolution image such as .png or .jpg by 1st November 2018.

**Exhibitor pass:** Exhibitor pass entitled to admission of RFM2018 conference (excluding tutorial session on 17th December 2018), morning and afternoon breaks, lunch during RFM2018 (18-19th December 2018) and conference dinner. Only the registered exhibitor is allowed at the exhibition booth, and sharing of pass is prohibited. Additional exhibitor pass is available for additional cost of RM1000.

**Product Demonstration/Exhibition:** Platinum and Gold sponsors are entitled to demonstrate the company's products at the designated exhibition area. The exhibition is from 9am until 6pm on the 18th and 9am until 5pm on 19th December 2018. The setting up time is on 17th December 2018, 7pm – 10 pm (upon hotel confirmation).

Platinum Sponsors. will be provided with two (2) tables and four (4) chairs. Gold sponsor and exhibitor will be provided with one (1) table and two (2) chairs. The size of the table is 2ft x 6 ft and the maximum loading of 60kg per table. The location of exhibition space is based on first come first first serve basis.

Organised by: AP/MTT/EMC Joint Chapter, IEEE Malaysia



Supported by:





penang convention &

exhibition

hureau